



Product Change Notification: MAAN-07VGQN798

Date:

14-Feb-2025

Product Category:

Memory

Notification Subject:

CCB 7401 Final Notice: Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material and G631BQF as a new mold compound material for AT24C32D-MAHM-T, AT24C32D-MAHM-E, AT24C32E-MAHM-T, AT24C64D-MAHM-T and AT24C64D-MAHM-E catalog part numbers (CPN) available in 8L UDFN (2x3x0.6mm) package assembled at ATP7 assembly site.

Affected CPNs:

[**MAAN-07VGQN798_Affected_CPN_02142025.pdf**](#)

[**MAAN-07VGQN798_Affected_CPN_02142025.csv**](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material and G631BQF as a new mold compound material for AT24C32D-MAHM-T, AT24C32D-MAHM-E, AT24C32E-MAHM-T, AT24C64D-MAHM-T and AT24C64D-MAHM-E catalog part numbers (CPN) available in 8L UDFN (2x3x0.6mm) package assembled at ATP7 assembly site.

Pre and Post Summary Changes:

	Pre Change		Post Change	
Assembly Site	Microchip Technology Thailand	Amkor Technology Philippines (P3/P4), INC.	Microchip Technology Thailand	Amkor Technology Philippines

	(MMT)	(ATP7)	(MMT)	(P3/P4), INC. (ATP7)
Wire Material	CuPdAu	PdCu	CuPdAu	CuPdAu
Die Attach Material	8600	CRM-1085A or AMK-06	8600	AMK-06
Molding Compound Material	G700LTD	G700Y	G700LTD	G631BQF
Lead-Frame Material	EFTEC-64T	C7025	EFTEC-64T	C7025

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new wire material and G631BQF as a new mold compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: 31 March 2025 (date code: 2514)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2025					March 2025				
Work Week	05	06	07	08	09	10	11	12	13	14
Qual Report Availability			X							
Final PCN Issue Date			X							

Estimated Implementation Date											X
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Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 14, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_MAAN-07VGQN798 Qual Report-ATP7.pdf**](#)
[**PCN_MAAN-07VGQN798 Qual Report-MMT.pdf**](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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